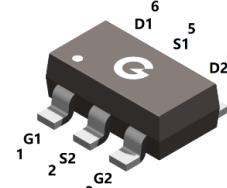
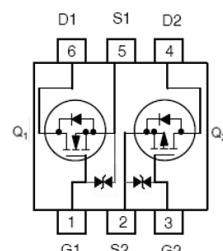


## Features

- Low on-resistance
- ESD protected
- High speed switching
- Low leakage current
- HBM: JESD22-A114-B: 2
- RoHS compliant with Halogen-free

**HF**



**SOT-23-6L**

## Mechanical Data

- Case: SOT-23-6L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
2N7172-6L	SOT-23-6L	3000 pcs / Tape & Reel	7172

## Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Q1	Q2	Unit
Drain-to-Source Voltage	$V_{DSS}$	60	-60	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current ( $T_A = 25^\circ\text{C}$ ) <sup>*1</sup>	$I_D$	0.55	-0.35	A
Continuous Drain Current ( $T_A = 70^\circ\text{C}$ ) <sup>*1</sup>		0.44	-0.28	A
Pulsed Drain Current ( $t_p = 10\mu\text{s}$ , $T_A = 25^\circ\text{C}$ )	$I_{DM}$	2.2	-1.4	A
Single Pulse Avalanche Energy <sup>*3</sup>	$E_{AS}$	0.11	0.3	mJ
Power Dissipation ( $T_A = 25^\circ\text{C}$ ) <sup>*1</sup>	$P_D$	1		W
Operating Junction Temperature Range	$T_J$	$-55 \sim +150$		$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	$-55 \sim +150$		$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	70	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Air <sup>*1</sup>	$R_{\theta JA}$	-	-	125	$^\circ\text{C}/\text{W}$

Electrical Characteristics-Q<sub>1</sub> (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±10	μA
<b>On Characteristics</b>						
R <sub>DSON</sub>	Drain-Source On-resistance <sup>*2</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.5A	-	1	1.5	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A	-	1.2	4	Ω
V <sub>Gsth</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	2.5	V
<b>Dynamic Characteristics</b>						
g <sub>f</sub>	Transconductance	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.2A	-	0.5	-	S
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 20V f = 1.0MHz	-	26.7	-	pF
C <sub>oss</sub>	Output Capacitance		-	7.1	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	2.2	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time <sup>*4</sup>	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V R <sub>L</sub> = 150Ω R <sub>G</sub> = 25Ω I <sub>D</sub> = 0.2A	-	6	-	nS
t <sub>r</sub>	Turn-on Rise Time <sup>*4</sup>		-	5	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time <sup>*4</sup>		-	25	-	
t <sub>f</sub>	Turn-Off Fall Time <sup>*4</sup>		-	15	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DS</sub> = 10V V <sub>GS</sub> = 4.5V I <sub>D</sub> = 0.2A	-	0.44	-	nC
Q <sub>GS</sub>	Gate to Source Charge		-	0.14	-	nC
Q <sub>GD</sub>	Gate to Drain (Miller) Charge		-	0.2	-	nC
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>SD</sub> = 0.3A, V <sub>GS</sub> = 0V	-	0.85	1.2	V

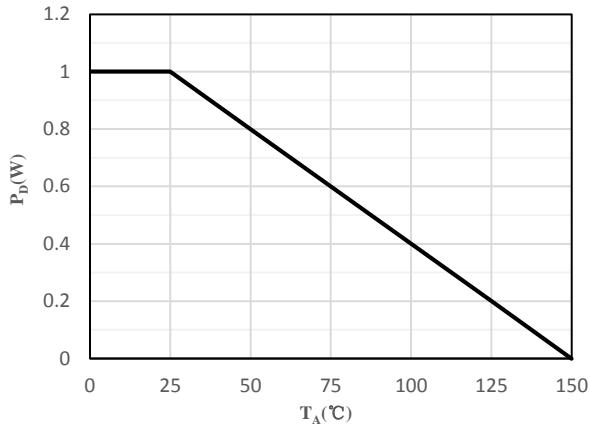
Electrical Characteristics-Q<sub>2</sub> (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V	-	-	-1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±10	μA
<b>On Characteristics</b>						
R <sub>DSON</sub>	Drain-Source On-resistance <sup>*2</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -0.1A	-	1.8	4	Ω
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -0.1A	-	2.3	5	
V <sub>GSTH</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1	-1.5	-2	V
<b>Dynamic Characteristics</b>						
g <sub>fS</sub>	Transconductance	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.2A	-	0.5	-	S
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = -20V f = 1.0MHz	-	39	-	pF
C <sub>OSS</sub>	Output Capacitance		-	12	-	
C <sub>RSS</sub>	Reverse Transfer Capacitance		-	2	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time <sup>*4</sup>	V <sub>DS</sub> = -15V R <sub>L</sub> = -50Ω I <sub>D</sub> = -2.5A	-	2.5	-	ns
t <sub>r</sub>	Turn-on Rise Time <sup>*4</sup>		-	1	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time <sup>*4</sup>		-	16	-	
t <sub>f</sub>	Turn-Off Fall Time <sup>*4</sup>		-	8	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DS</sub> = -25V V <sub>GS</sub> = -4.5V I <sub>D</sub> = -0.2A	-	2	-	nC
Q <sub>GS</sub>	Gate to Source Charge		-	0.7	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge		-	0.5	-	
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>S</sub> = -0.2A, V <sub>GS</sub> = 0 V	-	-0.87	-1.4	V

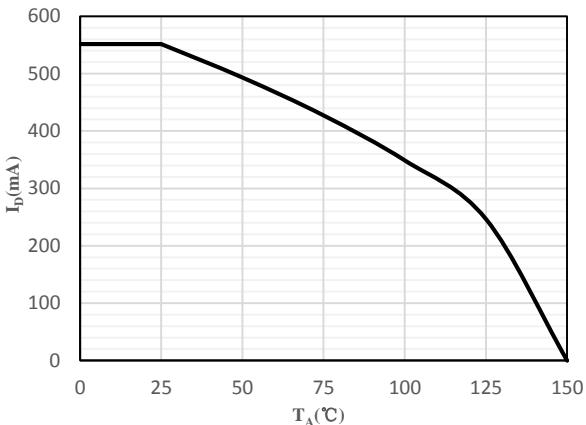
Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E<sub>AS</sub> data shows Max. rating. N: The test condition is V<sub>DD</sub> = 30V, V<sub>GS</sub> = 10V, L = 0.1mH;  
P: The test condition is V<sub>DD</sub> = -30V, V<sub>GS</sub> = -10V, L = 0.1mH
4. Guaranteed by design, not subject to production

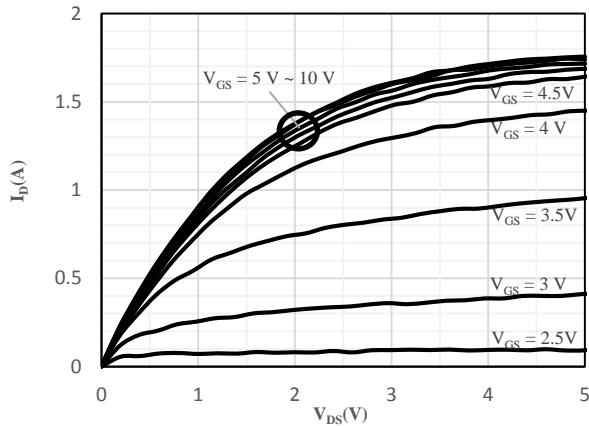
### Ratings and Characteristics Curves-Q<sub>1</sub> (@ T<sub>A</sub> = 25°C unless otherwise specified)



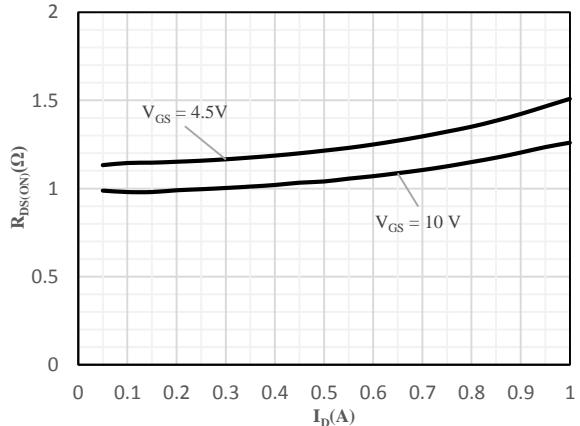
**Fig 1 Power Dissipation**



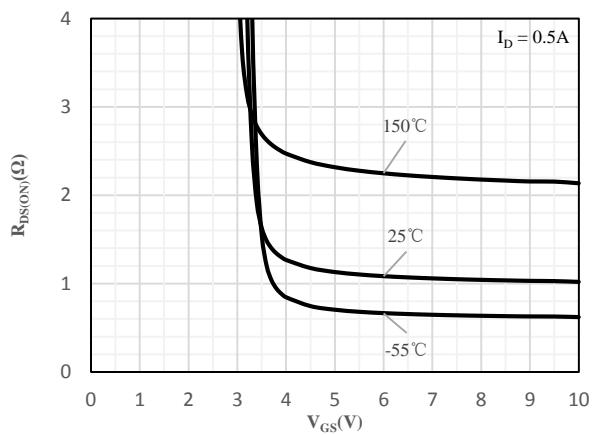
**Fig 2 Drain Current**



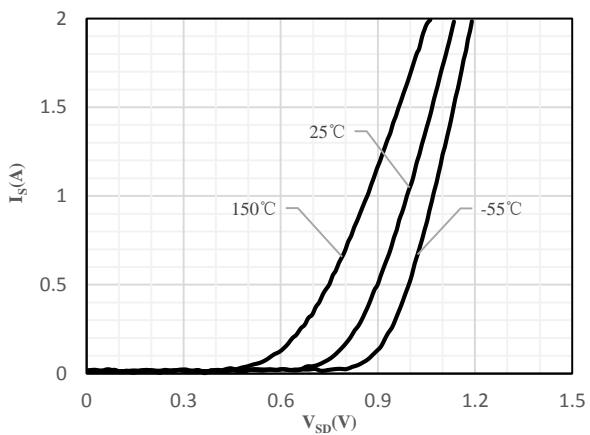
**Fig 3 Typical Output Characteristics**



**Fig 4 On-Resistance vs. Drain Current  
and Gate Voltage**



**Fig 5 On-Resistance vs. Gate-Source Voltage**



**Fig 6 Body-Diode Characteristics**

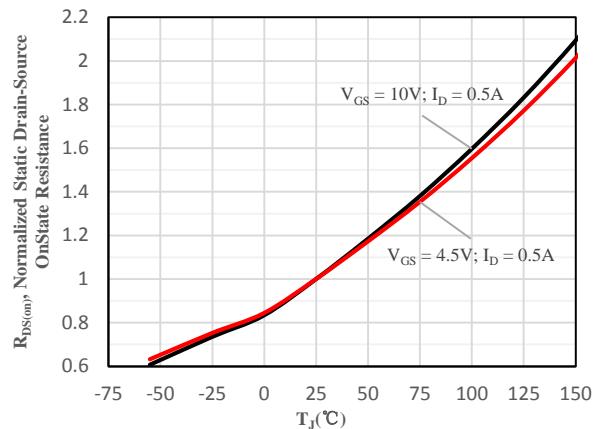


Fig 7 Normalized On-Resistance vs. Junction Temperature

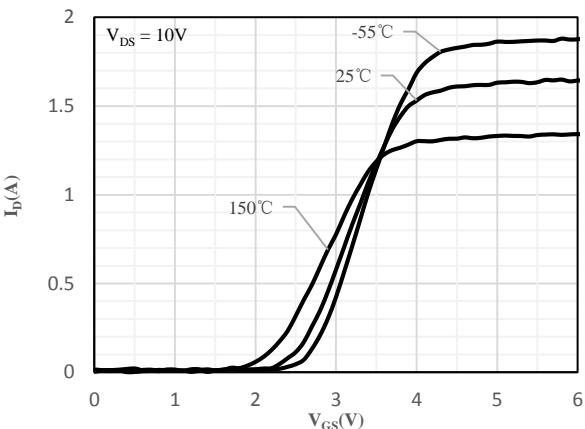


Fig 8 Transfer Characteristics

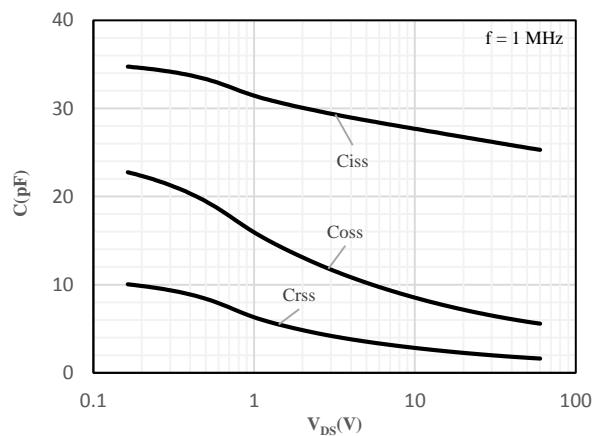


Fig 9 Capacitance Characteristics

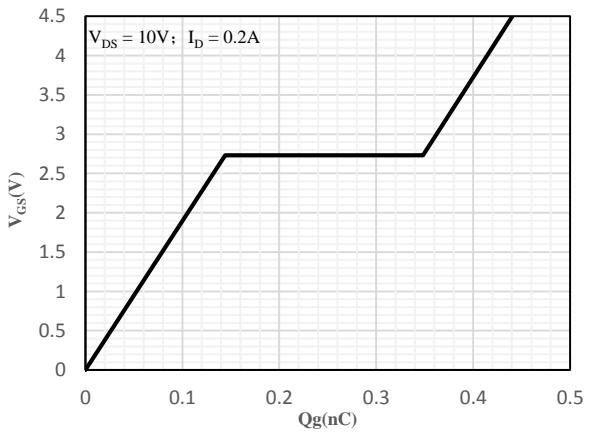


Fig 10 Gate-Charge Characteristics

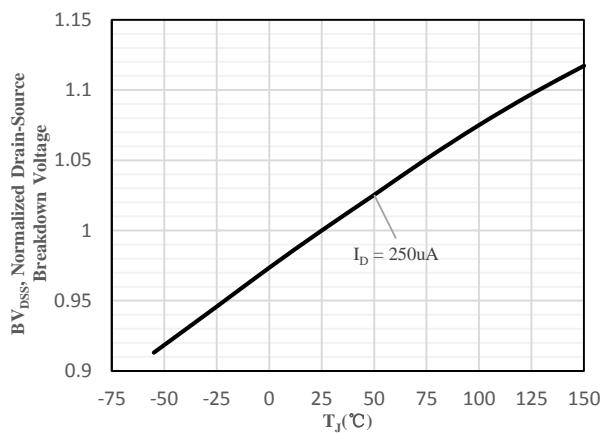


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

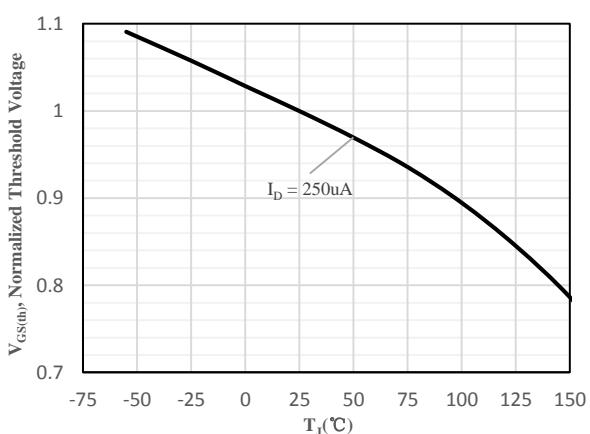


Fig 12 Normalized  $V_{GS(th)}$  vs. Junction Temperature

### Ratings and Characteristics Curves-Q<sub>2</sub> (@ T<sub>A</sub> = 25°C unless otherwise specified)

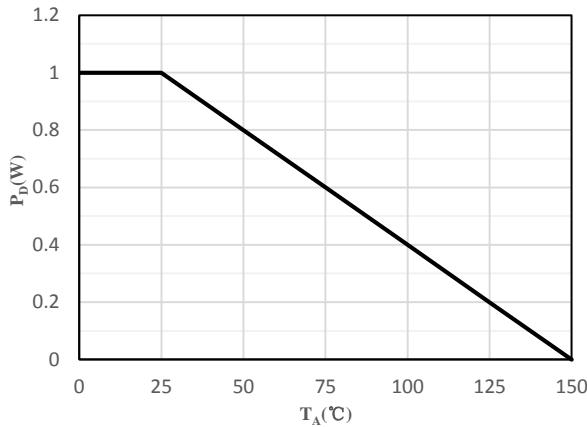


Fig 1 Power Dissipation

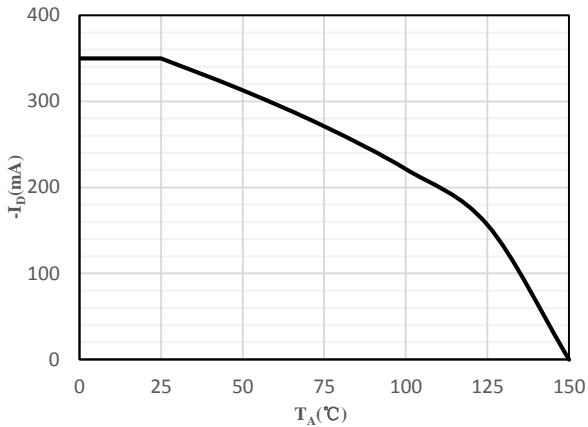


Fig 2 Drain Current

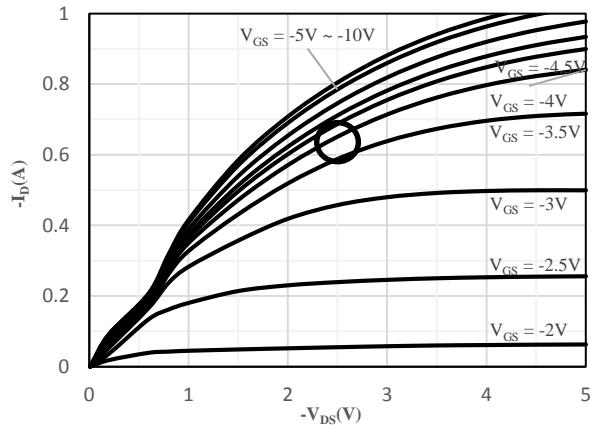


Fig 3 Typical Output Characteristics

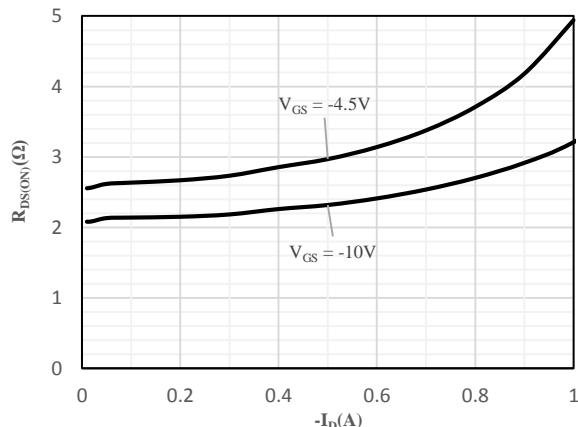


Fig 4 On-Resistance vs. Drain Current

and Gate Voltage

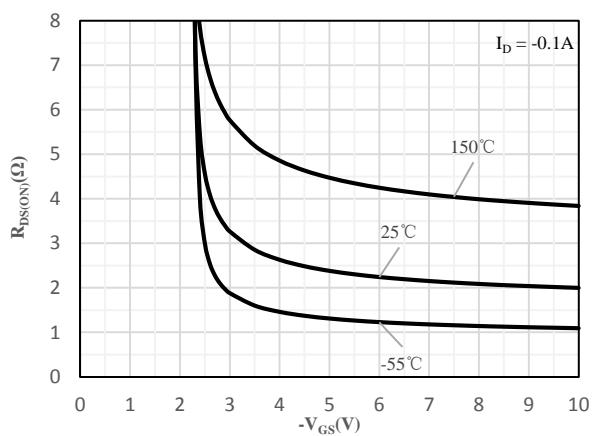


Fig 5 On-Resistance vs. Gate-Source Voltage

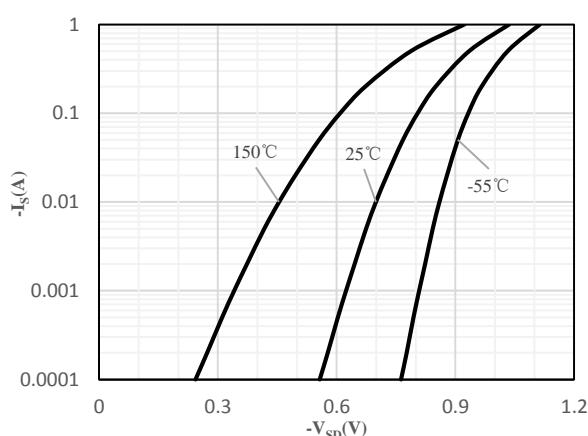


Fig 6 Body-Diode Characteristics

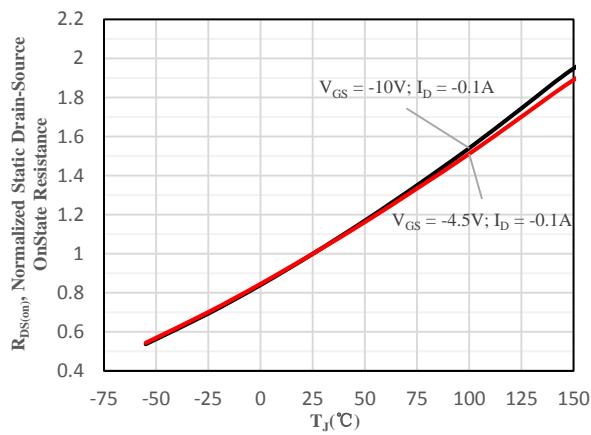


Fig 7 Normalized On-Resistance vs. Junction Temperature

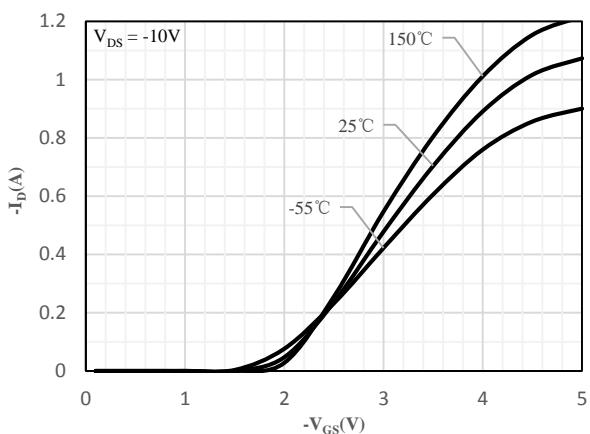


Fig 8 Transfer Characteristics

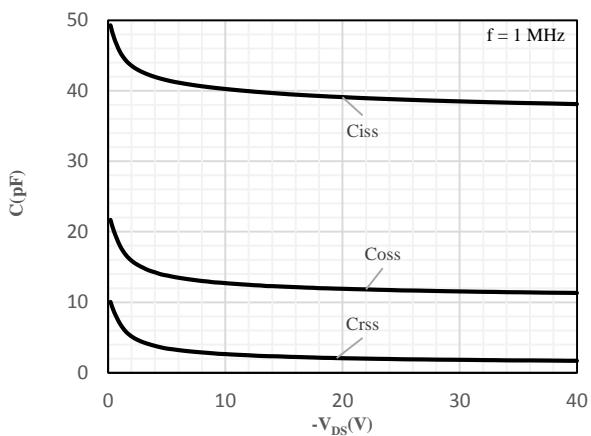


Fig 9 Capacitance Characteristics

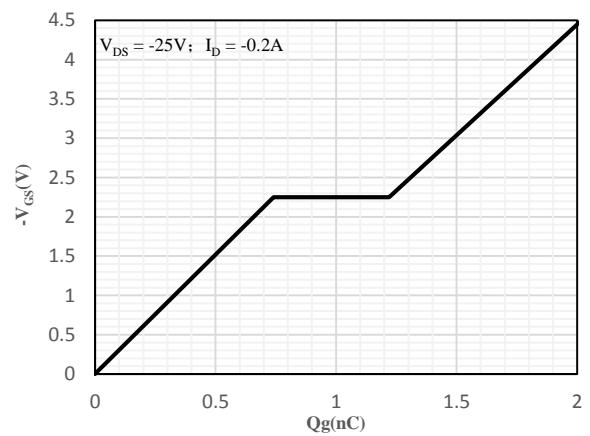


Fig 10 Gate-Charge Characteristics

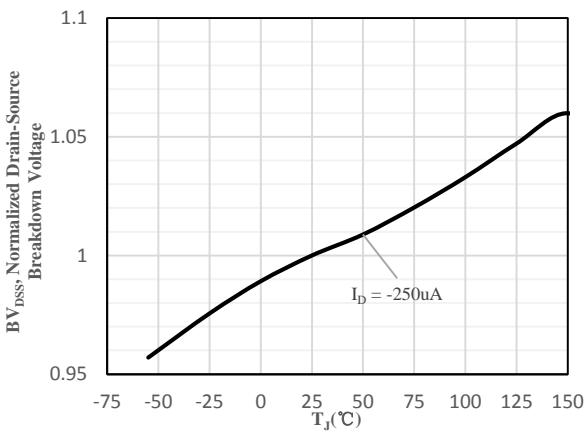


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

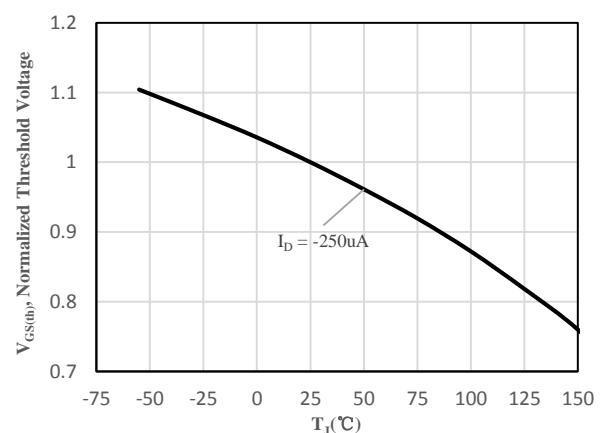
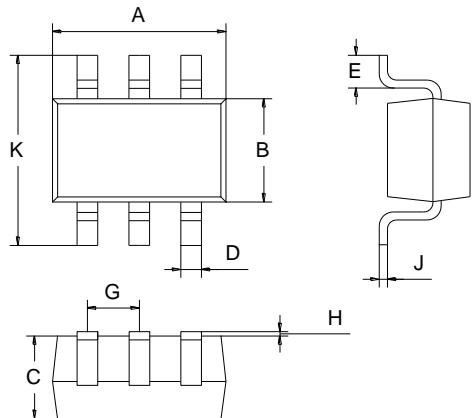


Fig 12 Normalized  $V_{GS(th)}$  vs. Junction Temperature

### Package Outline Dimensions (Unit: mm)



SOT-23-6L		
Dimension	Min.	Max.
A	2.80	3.00
B	1.50	1.70
C	1.00	1.20
D	0.35	0.45
E	0.35	0.55
G	0.90	1.00
H	0.02	0.10
J	0.10	0.20
K	2.60	3.00

### Package Outline Dimensions (Unit: mm)

SOT-23-6L

